

RELIABILITY REPORT
FOR
MAX6775LTA+
PLASTIC ENCAPSULATED DEVICES

November 30, 2009

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.
SUNNYVALE, CA 94086

Approved by
Ken Wendel
Quality Assurance
Director, Reliability Engineering

Conclusion

The MAX6775LTA+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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I. Device Description

A. General

The MAX6775-MAX6781 low-power, 1%-accurate battery monitors are available in the ultra-small μ DFN package (1.0mm x 1.5mm) and SC70 packages. These low-power devices are ideal for monitoring single lithium-ion (Li+) cells, or multicell alkaline/NiCd/NiMH power sources. These devices offer single (MAX6775/MAX6776/MAX6777/MAX6778) or dual (MAX6779/MAX6780/MAX6781) low-battery outputs and feature fixed or resistor-adjustable hysteresis. Hysteresis eliminates the output chatter sometimes associated with battery voltage monitors, usually due to input-voltage noise or battery terminal voltage recovery after load removal. These devices are available in several versions: with single- or dual-voltage monitors, and with fixed or adjustable hysteresis. The MAX6775/MAX6776 offer a single battery monitor and factory-set hysteresis of 0.5%, 5%, or 10%. The MAX6779/MAX6780/MAX6781 have two battery monitors in a single package and factory-set hysteresis of 0.5%, 5%, or 10%. The MAX6777/MAX6778 offer a single battery monitor with external inputs for the rising and falling thresholds, allowing external hysteresis control. For convenient interface with system power circuitry or microprocessors, both open-drain and push-pull outputs are available. The single-channel devices are available with open-drain or push-pull outputs. The dual-channel devices are available with both outputs open-drain, both outputs push-pull, or one of each (see the *Selector Guide* in the full data sheet). This family of devices is offered in small 5-pin SC70 and ultra-small 6-pin μ DFN packages, and is fully specified over the -40°C to $+85^{\circ}\text{C}$ extended temperature range.

II. Manufacturing Information

A. Description/Function:	Low-Power, 1%-Accurate Battery Monitor in μ DFN and SC70 Packages
B. Process:	B6
C. Number of Device Transistors:	
D. Fabrication Location:	California
E. Assembly Location:	Thailand
F. Date of Initial Production:	July 23, 2005

III. Packaging Information

A. Package Type:	6-pin uDFN
B. Lead Frame:	Substrate
C. Lead Finish:	Gold
D. Die Attach:	Non-conductive
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-9000-1855
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Multi Layer Theta Ja:	477°C/W

IV. Die Information

A. Dimensions:	31 X 30 mils
B. Passivation:	$\text{Si}_3\text{N}_4/\text{SiO}_2$ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	0.6 microns (as drawn)
F. Minimum Metal Spacing:	0.6 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

- A. Quality Assurance Contacts: Ken Wendel (Director, Reliability Engineering)
Bryan Preeshl (Managing Director of QA)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 45 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 23.9 \times 10^{-9}$$
$$\lambda = 23.9 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maxim-ic.com/qa/reliability/monitor>. Cumulative monitor data for the B6 Process results in a FIT Rate of 0.06 @ 25C and 1.04 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The MS90 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2500 V per JEDEC JESD22-A114. Latch-Up testing has shown that this device withstands a current of +/-250 mA.

Table 1
Reliability Evaluation Test Results

MAX6775LTA+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)				
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	45	0
Moisture Testing (Note 2)				
HAST	Ta = 130°C RH = 85% Biased Time = 96hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2)				
Temperature Cycle	-55°C/125°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process data